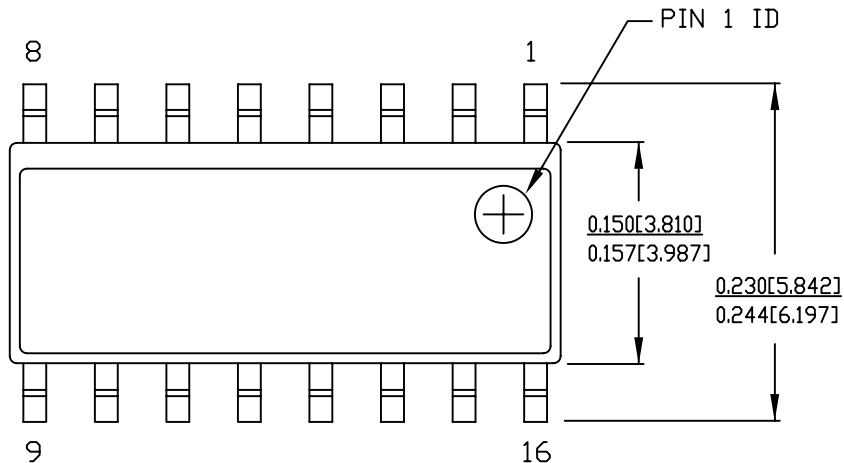


16 Lead (150 Mil) SOIC

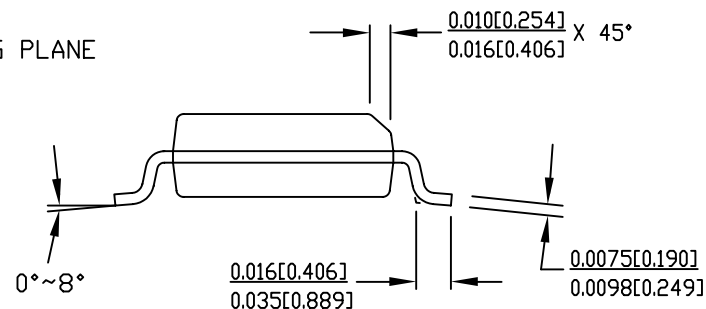
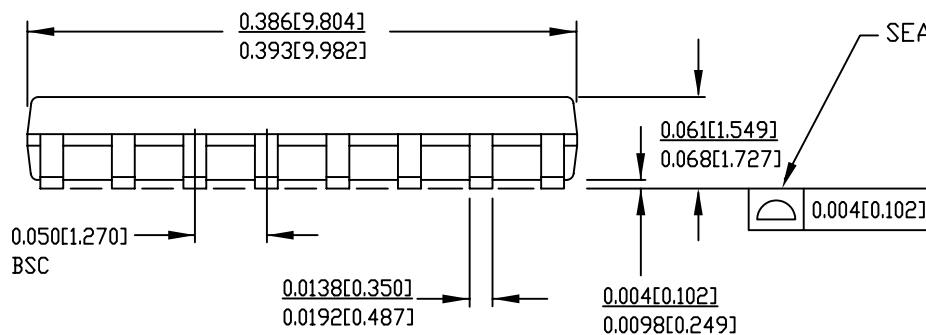


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	1129	NEW RELEASE	02/23/95	N/A
1	-	*A	49416	CHG. TITLE	04/03/97	N/A
1	-	*B	128915	ADD MM DIM./ ADD JEDEC #/ ADD SZ PART # / ADD PACKAGE WEIGHT	08/05/03	N/A
1	-	*C	2780429	CHANGED TO STANDARD DWG./TITLE FROM 16LD (150 MIL) SOIC PKG PACKAGE OUTLINE, 16L SOIC 150 MIL S16.15/SZ16.15.	10/07/09	BZG
1	-	*D	3357783	Update spec for sunset review no change	08/30/11	QAD
1	-	*E	3735784	Changed pkg. weight 0.15gm to "refer to PMDD spec 001-04308"	09/05/12	QAD

NOTE:

1. DIMENSIONS IN INCHES[MM] MAX.
2. REFERENCE JEDEC MS-012
3. PACKAGE WEIGHT : refer to PMDD spec. 001-04308

PART #	
S16.15	STANDARD PKG.
SZ16.15	LEAD FREE PKG.



THIS DRAWING CONTAINS INFORMATION WHICH IS THE PROPRIETARY PROPERTY OF CYPRESS SEMICONDUCTOR CORPORATION. THIS DRAWING IS RECEIVED IN CONFIDENCE AND ITS CONTENTS MAY NOT BE DISCLOSED WITHOUT WRITTEN CONSENT OF CYPRESS SEMICONDUCTOR CORPORATION.

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE: DECIMALS .XX ± 0.05 .XXX ± .0005 .XXXX ± .0001 ANGLES ± 1°	DESIGNED BY	HTN	DATE	08/05/03	CYPRESS Company Confidential				
	DRAWN BY	HTN	DATE	08/05/03					
	CHECKED BY	XANC	DATE	09/05/12					
	APPROVED BY	QAD	DATE	09/05/12					
MATERIAL	N/A	APPROVED BY	EDCA	DATE	09/05/12	TITLE	PACKAGE OUTLINE, 16L SOIC 150 MIL S16.15/SZ16.15		
FINISH	N/A	APPROVED BY	PRC	DATE	09/05/12	SIZE	A	PART NO.	S16.15/SZ16.15
						DWG NO	51-85068		
						REVISION	*E		
						SCALED TO FIT	N/A		
						SHEET	1 OF 1		